

Application No. 10/065,016  
Filed: September 12, 2002  
Page 3 of 9

Examiner: L. Cruz  
Art Unit: 2841

This listing of claims will replace all prior versions and listings of claims in the application:

**Listing of Claims:**

Claim 1 (Currently Amended): An integrated circuit package device having a plurality of contact points, wherein the plurality of contact points includes an inner portion of said contact points and an outer portion of said contact points, the integrated circuit package device comprising at least one of the following:

(i) a majority of power supply contacts configured substantially in an extremity of said outer portion;

(ii) a majority of timing or frequency contacts configured substantially in said outer portion; and

(iii) ~~(iv)~~ a majority of data or high speed signal contacts configured substantially in an inner side of said outer portion.

Claim 2 (Previously Amended): The integrated circuit package device according to Claim 1, wherein ground contacts are further provided along a bisectonal axis through said outer portion to facilitate a ground path from outside an area of the integrated circuit package device to said inner portion.

Claim 3 (Original): The integrated circuit package device according to Claim 1, wherein said inner portion is formed substantially of ground contact points to effect a ground plane.

Claim 4 (Previously Amended): The integrated circuit package device according to Claim 1, wherein, for one or more signals associated with (i) to (iii), all of said respective contacts are configured in the respective manner described in one or more of (i) to (iii).

Claim 5 (Previously Amended): A printed circuit board having a plurality of tracks for operably coupling electrical signals to a plurality of contact points of at least one integrated circuit package device, wherein the plurality of contact points includes an

Application No. 10/065,016  
Filed: September 12, 2002  
Page 4 of 9

Examiner: L. Cruz  
Art Unit: 2841

inner portion of contact points and an outer portion of contact points, the printed circuit board comprising at least one of the following:

- (i) a majority of power supply contacts configured substantially in an extremity of said outer portion;
- (ii) a majority of timing or frequency contacts configured substantially in said outer portion ; and
- (iii) a majority of data or high speed signal contacts configured substantially in an inner side of said outer portion.

Claim 6 (Previously Amended): The printed circuit board according to Claim 5, wherein ground contacts are further provided along a bisectonal axis, through said outer portion to facilitate a ground path from outside an area of the integrated circuit package device to said inner portion.

Claim 7 (Original): The printed circuit board according to Claim 5, wherein said inner portion is formed substantially of ground contact points to effect a ground plane.

Claim 8 (Previously Amended): The printed circuit board according to Claim 5, wherein, for one or more signals associated with (i) to (iii), all of said respective contacts of said integrated circuit package device are configured in the respective manner described in one or more of (i) to (iii).

Claim 9 (Previously Amended): An electrical or electronic device comprising the integrated circuit package device according to claim 5.

Claim 10 (Previously Added): The integrated circuit package device according to claim 1 further comprising at least one ground contact configured substantially in said inner portion.

Claim 11 (Previously Added): The printed circuit board according to claim 5 further comprising at least one ground contact configured substantially in said inner portion.

Application No. 10/065,016  
Filed: September 12, 2002  
Page 5 of 9

Examiner: L. Cruz  
Art Unit: 2841

Claim 12 (Previously Added): The integrated circuit package device according to claim 1 wherein the inner portion and the outer portion are two distinct regions separated by a space.

Claim 13 (Previously Added): The printed circuit board according to claim 5 wherein the inner portion and the outer portion are two distinct regions separated by a space.

Claim 14 (New): An arrangement of a plurality of contact points in one of an integrated circuit package device and a printed circuit board wherein the plurality of contact points includes an inner portion of said contact points and an outer portion of said contact points, and at least one of the following

(i) a majority of power supply contacts is configured substantially in an extremity of said outer portion;

(ii) a majority of timing or frequency contacts is configured substantially in said outer portion; and

(iii) a majority of data or high speed signal contacts is configured substantially in an inner side of said outer portion.

Claim 15 (new): An integrated circuit package device according to claim 1 comprising two or more of the following:

(i) a majority of power supply contacts configured substantially in an extremity of said outer portion;

(ii) a majority of timing or frequency contacts configured substantially in said outer portion; and

(iii) a majority of data or high speed signal contacts configured substantially in an inner side of said outer portion.

Claim 16 (new): An integrated circuit package device according to claim 1 comprising all of the following:

(i) a majority of power supply contacts configured substantially in an extremity of said outer portion;

Application No. 10/065,016  
Filed: September 12, 2002  
Page 6 of 9

Examiner: L. Cruz  
Art Unit: 2841

(ii) a majority of timing or frequency contacts configured substantially in said outer portion; and

(iii) a majority of data or high speed signal contacts configured substantially in an inner side of said outer portion.

Claim 17 (new): An integrated circuit package device according to claim 15 wherein the inner portion and the outer portion are two distinct regions separated by a space.

Claim 18 (new): An integrated circuit package device according to claim 16 wherein the inner portion and the outer portion are two distinct regions separated by a space.

Claim 19 (new): An integrated circuit package device according to claim 16 and further comprising a majority of ground contacts configured substantially in said inner portion.

Claim 20 (new): A printed circuit board according to claim 5 comprising two or more of the following:

(i) a majority of power supply contacts configured substantially in an extremity of said outer portion;

(ii) a majority of timing or frequency contacts configured substantially in said outer portion; and

(iii) a majority of data or high speed signal contacts configured substantially in an inner side of said outer portion.

Claim 21 (new): A printed circuit board according to claim 5 comprising all of the following:

(i) a majority of power supply contacts configured substantially in an extremity of said outer portion;

(ii) a majority of timing or frequency contacts configured substantially in said outer portion; and

Application No. 10/065,016  
Filed: September 12, 2002  
Page 7 of 9

Examiner: L. Cruz  
Art Unit: 2841

(iii) a majority of data or high speed signal contacts configured substantially in an inner side of said outer portion.

Claim 22 (new): A printed circuit board according to claim 20 wherein the inner portion and the outer portion are two distinct regions separated by a space.

Claim 23 (new): A printed circuit board according to claim 21 wherein the inner portion and the outer portion are two distinct regions separated by a space.

Claim 24 (new): A printed circuit board according to claim 5 and further comprising a majority of ground contacts configured substantially in said inner portion.

Claim 25 (new): An electrical or electronic device comprising the integrated circuit package device according to claim 15.

Claim 26 (new): An electrical or electronic device comprising the integrated circuit package device according to claim 16.

Claim 27 (new): An electrical or electronic device comprising the integrated circuit package device according to claim 17.